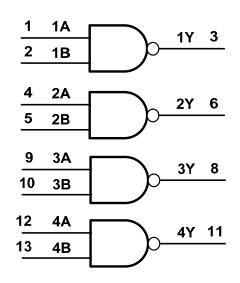


Pin Descriptions

Pin Number	Pin Name	Description
1	1A	Data Input
•		
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Inp	Output	
Α	В	Y
Н	Н	L
L	Х	Н
Х	L	Н

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to +7.0	V
VI	Input Voltage Range note 4	-0.5 to +7.0	V
l _{IK}	Input Clamp Current VI < 0V	-20	mA
I _{OK}	Output Clamp Current V _O < -0V	-50	mA
Io	Continuous Output Current - 0.5V < V _O V _{CC} +0.5V	±25	mA
Icc	Continuous Current Through V _{CC}	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 5)	$(@T_A = +25^{\circ}C, unless otherwise specified.)$
--	--

Symbol	Parameter	Conditions	Min	Max	Unit
Vcc	Supply Voltage	_	2.0	5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V _{CC}	V
		2.0V	—	-50	mA
	Lligh Lovel Output Current	2.3V to 2.7V	—	-2	μA
lон	High-Level Output Current	3.0V to 3.6V	—	-6	mA
		4.5V to 5.5V	_	-12	mA
		2.0V	—	50	μA
		2.3V to 2.7V	—	2	mA
IOL	Low-Level Output Current	3.0V to 3.6V	—	6	mA
		4.5V to 5.5V	—	12	mA
		2.3V to 2.7V	_	200	
Δt/ΔV	Input Transition Rise or Fall	3.0V to 3.6V	—	100	ns/V
		4.5V to 5.5V	—	20	
T _A	Operating Free-Air Temperature	_	-40	+125	°C

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V	T _A = -40°C	C to +85°C	T _A = -40°C	to +125°C	l lmit
Symbol	Farameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
		—	2.0V	1.5	—	1.5	—	
N/	High-Level Input	—	2.3V to 2.7V	V _{CC} X 0.7	—	V _{CC} X 0.7	—	V
VIH	Voltage	—	3.0V to 3.6V	V _{CC} X 0.7	—	V _{CC} X 0.7	—	
		—	4.5V to 5.5V	V _{CC} X 0.7	—	V _{CC} X 0.7	—	—
		—	2.0V	—	0.5	—	0.5	
N/	Low-Level Input	—	2.3V to 2.7V	—	V _{CC} X 0.3	—	V _{CC} X 0.3	V
VIL	Voltage	—	3.0V to 3.6V	—	V _{CC} X 0.3	_	V _{CC} X 0.3	
		—	4.5V to 5.5V	—	V _{CC} X 0.3	_	V _{CC} X 0.3	—
	High-Level	I _{OH} = -50µА	2.0V to 5.5V	V _{CC} -0.1	—	V _{CC} -0.1	—	
V		I _{OH} = -2mA	2.3V	2.0	—	2.0	—	v
V _{OH}	Output Voltage	I _{OH} = -6mA	3.0V	2.48	—	2.48	—	v
		I _{OH} = -12mA	4.5V	3.8	—	3.8	—	
		I _{OL} = 50μA	2.0V to 5.5V	—	0.1	—	0.1	
	Low-Level	I _{OL} = 2mA	2.3V	—	0.4	—	0.4	v
V _{OL}	Output Voltage	I _{OL} = 6mA	3.0V	—	0.44	—	0.44	v
		I _{OL} = 12mA	4.5V	—	0.55	—	0.55	
I _{OFF}	Power Down Leakage Current	$V_{\rm I}$ or $V_{\rm O}$ = 0 to 5.5V	0V	—	5	—	5	μA
II.	Input Current	V ₁ = GND or 5.5V	0 to 5.5V	—	±1	_	±1	μA
I _{CC}	Supply Current	$V_1 = GND \text{ or } V_{CC}$ $I_0 = 0$	5.5V	-	20	_	20	μA



Switching Characteristics

Symbol	Demonster	Test	t v		Γ _A = +25°C	;	-40°C to	o +85°C	-40°C to	+125°C	Unit
Symbol	Parameter	Conditions	Vcc	Min	Тур	Max	Min	Max	Min	Max	Unit
		Figure 1	2.5V ± 0.2V	_	7.1	12.9	1	15	1	16	
	t _{PD} Propagation Delay A _N to Y _N	Figure 1 C _L = 15pF	3.3V ± 0.3V	_	5	7.9	1	9.5	1	10.5	ns
4			5.0V ± 0.5V	_	3.6	5.5	1	6.5	1	7.5	
чРD		Figure 1	2.5V ± 0.2V	_	9.6	16.6	1	20	1	21	
		Figure 1 C _L = 50pF	3.3V ± 0.3V	_	6.9	11.4	1	13	1	14	ns
		CL - SOPF	5.0V ± 0.5V	_	4.9	7.5	1	8.5	1	9.5	

Operating Characteristics

T_A = +25°C

	Parameter	Test Conditions	V _{cc}	Тур	Unit
0	Power Dissipation	F = 10 MHz	3.3V	9.5	~ [
Cpd	Capacitance per Gate	$C_L = 50 pF$	5.0V	11	pF

Noise Characteristics

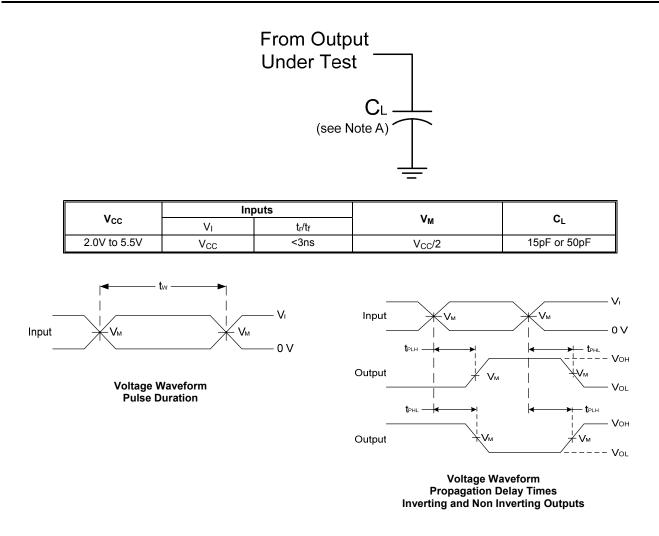
$V_{CC} = 3V, C_L =$	= 50pF, T _A = +25°C				
Symbol	Parameter	Min	Тур	Max	Unit
V _{OL(p)}	Quiet output, maximum dynamic V _{OL}	—	0.2	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}	—	-0.1	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}	—	3.1	—	V
V _{IH(D)}	High Level dynamic input voltage	2.31	_	_	V
V _{IL(D)}	Low Level dynamic input voltage	—	_	0.99	V

Package Characteristics

Symbol	Parameter	Test Conditions	Vcc	Min	Тур	Max	Unit
Ci	Input Capacitance	$V_i = V_{CC} - or GND$	2.0 to 5.5V		3.3	10	pF



Parameter Measurement Information

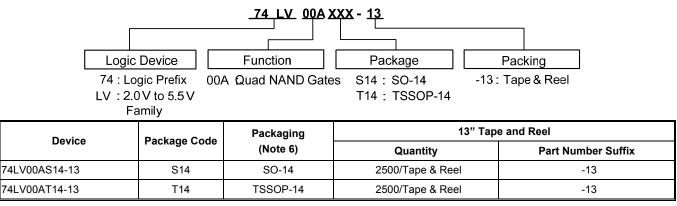


- Notes: A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate \leq 10MHz
 - C. Inputs are measured separately one transition per measurement
 - D. t_{PLH} and t_{PHL} are the same as t_{PD}

Figure 1 Load Circuit and Voltage Waveforms



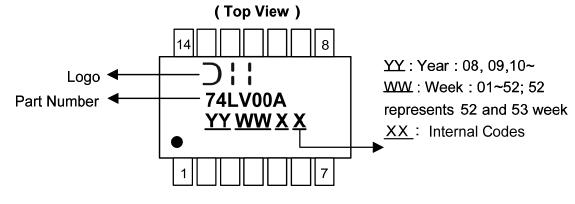
Ordering Information



Note: 6. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO14, TSSOP14



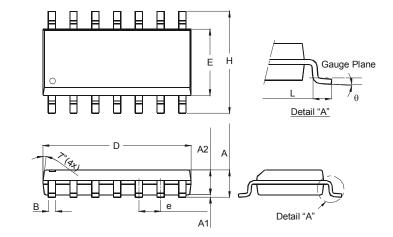
Part Number	Package
74LV00AS14	SO-14
74LV00AT14	TSSOP-14



Package Outline Dimensions (All Dimensions in mm)

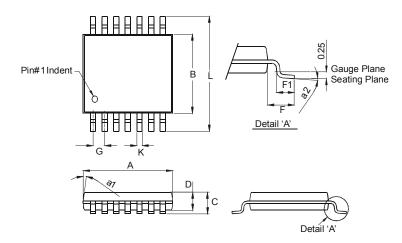
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

Package Type: SO-14



	SO-14					
Dim	Min	Max				
Α	1.47	1.73				
A1	0.10	0.25				
A2	1.45	Тур				
В	0.33	0.51				
D	8.53	8.74				
Е	3.80	3.99				
е	1.27	Тур				
Н	5.80	6.20				
L	0.38	1.27				
θ	0°	8°				
All Di	mensions	s in mm				

Package Type: TSSOP-14



TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
Α	4.9	5.10
В	4.30	4.50
С	_	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
κ	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

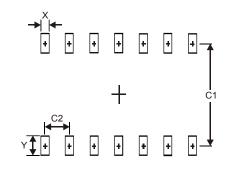
NEW PRODUCT



Suggested Pad Layout

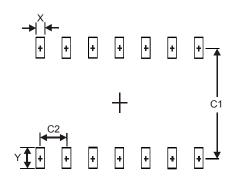
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

Package Type: SO-14



Dimensions	Value (in mm)
Х	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
Х	0.45
Y	1.45
C1	5.9
C2	0.65



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